SN54ABTH16245, SN74ABTH16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS662I - MARCH 1996 - REVISED MARCH 1999

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

description

The 'ABTH16245 devices are 16-bit noninverting external timing requirements.

3-state transceivers that provide synchronous two-way communication between data buses. The control-function implementation minimizes

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the devices so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16245 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABTH16245 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

SN54ABTH16245 . . . WD PACKAGE SN74ABTH16245...DGG, DGV, OR DL PACKAGE (TOP VIEW)

	$\overline{}$		_			
1DIR [1	\cup	48	b	10E	
1B1 [47	þ	1A1	
1B2	3		46	þ	1A2	
GND [4		45		GND	
1B3	5		44		1A3	
1B4			43	_	1A4	
V _{CC}			42	0	V_{CC}	
1B5			41		1A5	
1B6			40		1A6	
GND [1				GND	
1B7			38		1A7	
1B8			37		1A8	
2B1			36		2A1	
2B2			35		2A2	
GND [34		GND	
2B3			33		2A3	
2B4			32		2A4	
V _{CC}	18		31	P	V_{CC}	
2B5					2A5	
2B6					2A6	
GND [GND	
2B7					2A7	
2B8				_	2 <u>A8</u>	
2DIR [24		25	Ц	2 <mark>OE</mark>	
				•		

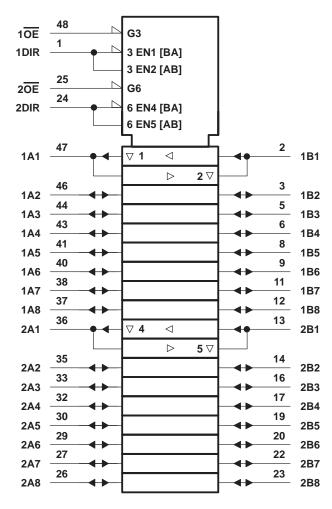
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FUNCTION TABLE (each 8-bit section)

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

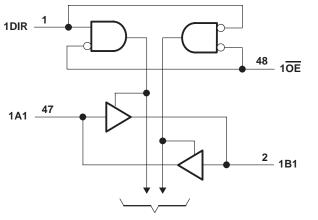
logic symbol†

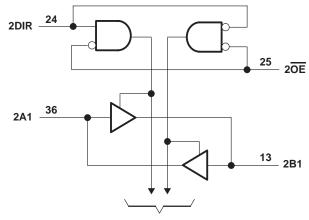


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





To Seven Other Channels To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABTH16245	96 mA
SN74ABTH16245	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

			SN54ABTI	116245	SN74ABTI	H16245	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
V _{IL}	V _{IL} Low-level input voltage					0.8	V
VI	Input voltage		0	Vcc	0	Vcc	V
ІОН	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51.

SN54ABTH16245, SN74ABTH16245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	RAMETER	TEST CO	ONDITIONS	Т	A = 25°C	;	SN54ABTI	H16245	SN74ABTI	116245	UNIT	
FAR	KAWETER	1231 00	RDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/-··		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
\/a.		V 45V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
l _l	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μА	
	A or B ports					±100		±100		±100		
1.0		V _{CC} = 4.5 V	V _I = 0.8 V	100			100		100		μА	
l(hold))	VCC = 4.5 V	V _I = 2 V	-100			-100		-100		μΑ	
1		$V_{CC} = 0 \text{ to } 1.9 \text{ V}$	$V_{O} = 0.5 \text{ V to } 2.7 \text{ V},$			±50**		±50**			μΑ	
IOZPU	J	$V_{CC} = 0 \text{ to } 2.1 \text{ V}$	OE = X			±50				±50		
		$V_{CC} = 1.9 \text{ V to } 0$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V},$			±50**		±50**			μА	
IOZPD)	V _{CC} = 2.1 V to 0	OE = X			±50				±50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
IO [‡]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	- 50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0$	ts $I_{O} = 0$,	Outputs low			32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
ΔICC§		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			6						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

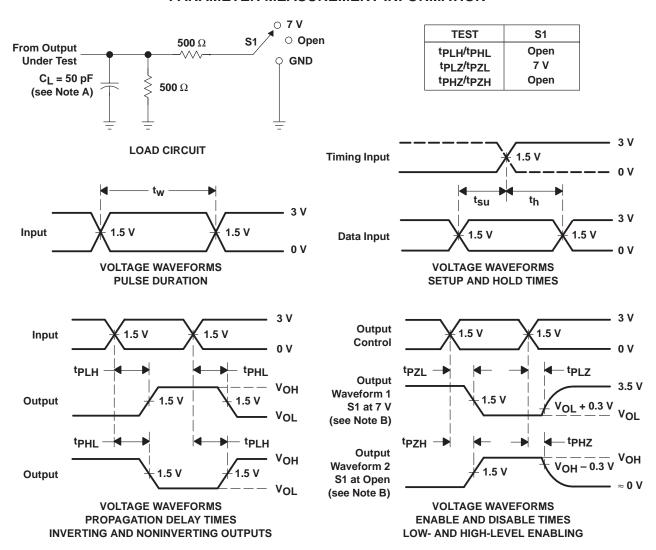
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.6	0.5	4.1	ns
^t PHL	7010	DOIA	1	2.3	3.8	0.5	4.4	115
^t PZH	ŌĒ	B or A	1	3.6	5.2	0.8	6.4	ns
t _{PZL}	OE	BULK	1	3.7	6.1	0.9	6.5	115
^t PHZ	ŌĒ	B or A	2	4.4	6.7	1.3	7.9	ns
^t PLZ	UE	BULK	1.5	3.3	4.7	1.4	5.6	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.4	1	3.9	ns
^t PHL	AOIB	BULK	1	2.3	3.7	1	4.2	115
^t PZH	ŌĒ	B or A	1	3.6	5.2	1	6.3	ns
t _{PZL}	OE OE	D OI A	1	3.7	5.4	1	6.4	115
^t PHZ	ŌĒ	B or A	2	4.4	5.8	2	6.3	ns
t _{PLZ}	UE UE	BULK	1.5	3.3	4.7	1.5	5.2	115

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
74ABTH16245DGGRG4	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
74ABTH16245DGGRG4.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGGR.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGVR	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM245
SN74ABTH16245DGVR.B	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM245
SN74ABTH16245DL	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DL.B	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLR.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLRG4	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLRG4.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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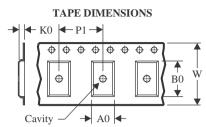
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

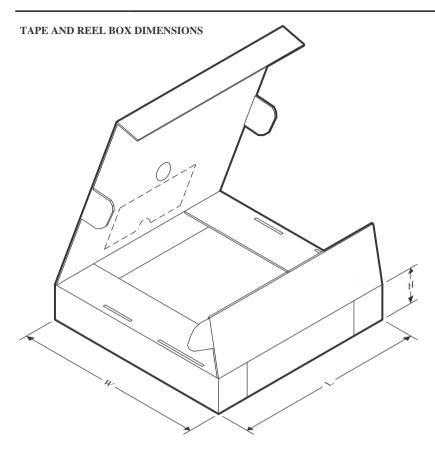


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ABTH16245DGGRG4	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABTH16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ABTH16245DLRG4	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



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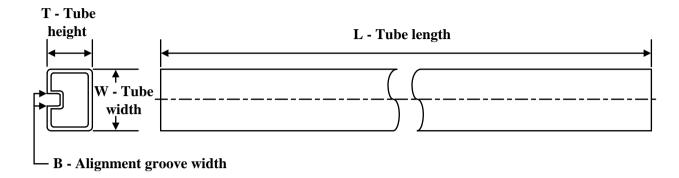
*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ABTH16245DGGRG4	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74ABTH16245DLR	SSOP	DL	48	1000	356.0	356.0	53.0
SN74ABTH16245DLRG4	SSOP	DL	48	1000	356.0	356.0	53.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABTH16245DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABTH16245DL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

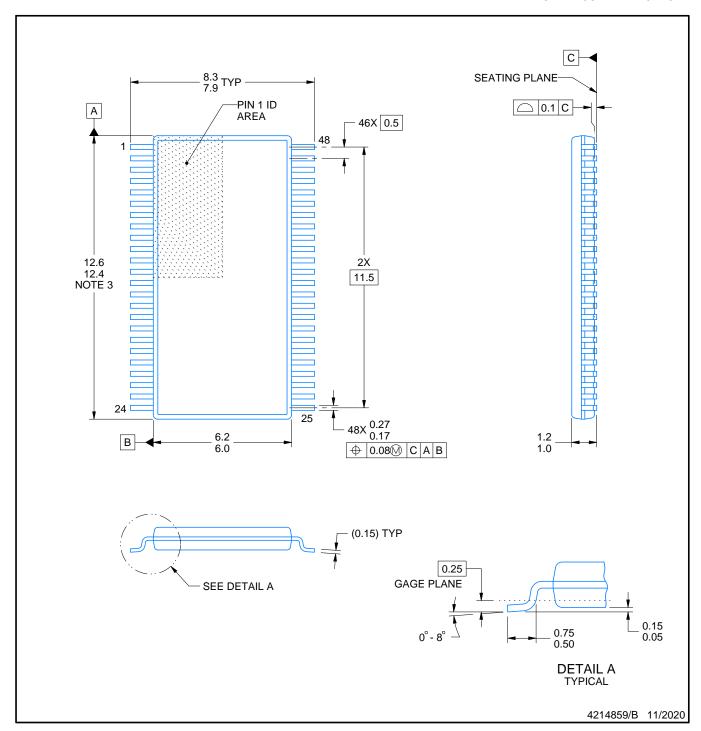
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



NOTES:

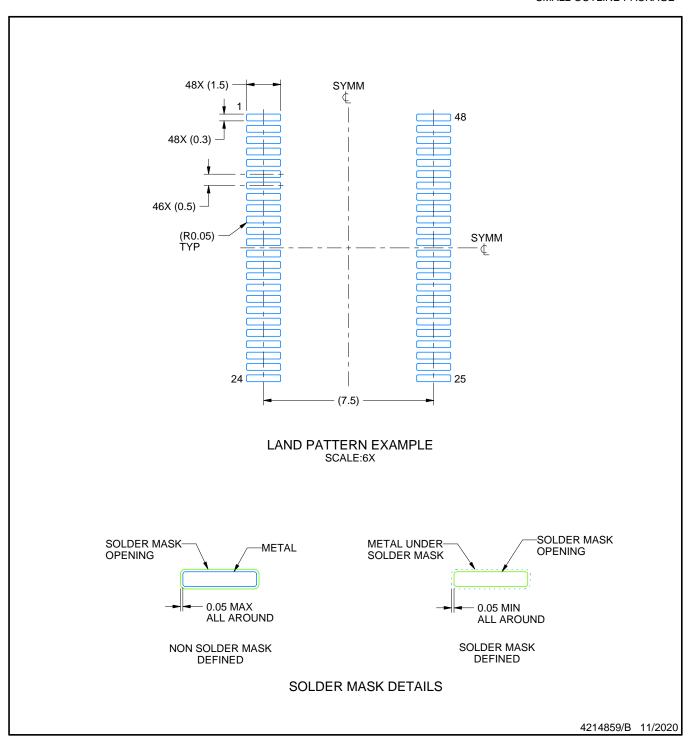
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

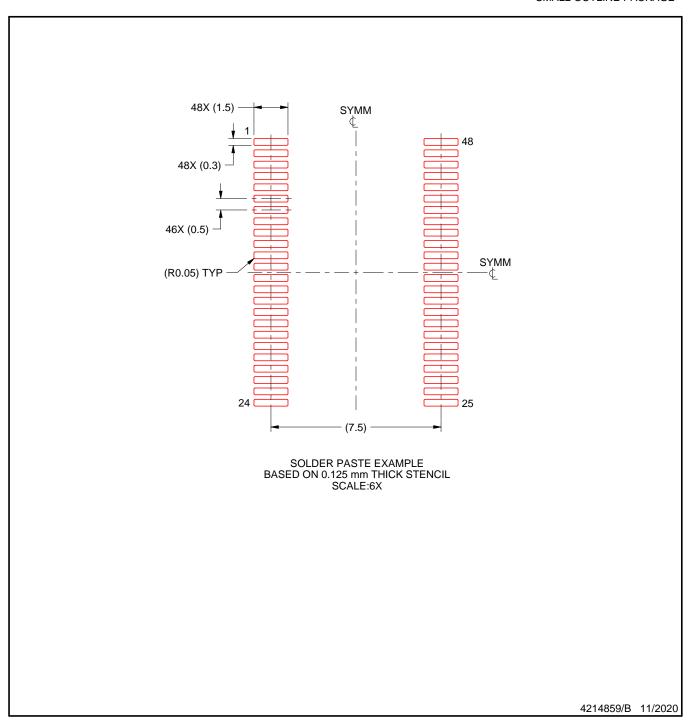


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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